JOB DESCRIPTION

Job Title

Micro Assembly Technician (Contract)

Employment Type

Contract (2–3 Months)

Job Purpose

The Micro Assembly Technician is responsible for supporting the Micro Assembly Engineer in the assembly, testing, and documentation of microwave/mmWave microelectronic products. The role involves performing die attach, wirebonding, equipment operation, and inspection activities in accordance with established work instructions and quality standards. The technician will assist in prototype builds, production activities, and process improvement initiatives to ensure products meet customer and company requirements.

Principal Accountabilities

1. Assist the Micro Assembly Engineer in die attach and wirebonding for prototype and production products.
2. Operate microelectronics assembly equipment, including die attach and wirebonding machines, in accordance with approved procedures and work instructions.
3. Perform operation and routine maintenance of assembly equipment and tooling.
4. Handle and assemble RF ICs, capacitors, inductors, substrates, and other microelectronic components using proper ESD controls and handling procedures.
5. Support prototype, first article, and pre-production builds by performing assembly and inspection tasks.
6. Conduct visual inspection of assembled products using microscopes and other inspection equipment to ensure compliance with workmanship standards.
7. Assist in rework and repair activities as required to meet product quality requirements.
8. Accurately record production and assembly data, ensuring traceability and compliance with quality system requirements.

9. Follow assembly drawings, process documentation, work instructions, and engineering specifications.
10. Support troubleshooting and investigation of assembly-related issues under the guidance of the Micro Assembly Engineer.
11. Maintain cleanliness and organization of workstations, tools, and equipment in accordance with ESD and 5S requirements.
12. Ensure all products are manufactured in accordance with company quality standards, customer requirements, and safety procedures.
13. Support implementation of continuous improvement activities to enhance productivity, quality, and efficiency.
14. Assist in inventory control of assembly consumables, materials, and tooling.
15. Perform any other duties assigned by the Micro Assembly Engineer or Manufacturing Supervisor.

Requirements

Education

- NITEC, Higher NITEC, Diploma, or equivalent qualification in:
    - Electronics Engineering
    - Electrical Engineering
    - Precision Engineering
    - Manufacturing Engineering
    - Related technical disciplines

Experience

- Experience in microelectronic assembly, semiconductor packaging, electronics manufacturing, or precision assembly is an advantage.
- Fresh graduates with relevant technical training are welcome to apply.

Technical Skills

- Basic knowledge of die attach and wirebonding processes.
- Ability to read and follow assembly drawings, work instructions, and process specifications.

- Experience working under microscope for precision assembly tasks is preferred.
- Knowledge of ESD control and handling of sensitive electronic devices.
- Familiarity with RF/microwave components is an advantage.
- Basic computer skills for production data entry and documentation.

Other Requirements

- Good manual dexterity and attention to detail.
- Ability to perform repetitive precision assembly tasks.
- Ability to work independently with minimal supervision after training.
- Team player with good communication skills.
- Able to work rotating shifts, including night shifts, weekends, and public holidays when required.
- Willingness to support overtime during production ramp-up or critical business needs.
- Comfortable working in a cleanroom and ESD-controlled environment.

Reporting To

Micro Assembly Staff Engineer

Work Environment

- Electronics manufacturing and microelectronics assembly environment.
- Use of microscopes, precision assembly tools, die attach equipment, and wirebonding machines.
- Handling of delicate RF and microelectronic components in ESD-controlled areas.